

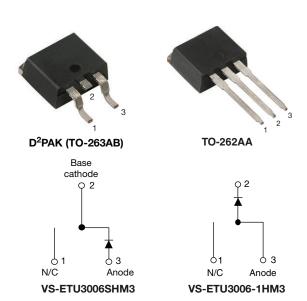
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Vishay Semiconductors

HALOGEN

FREE

Ultrafast Rectifier, 30 A FRED Pt®



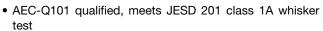
LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS						
Package	D ² PAK (TO-263AB), TO-262AA					
I _{F(AV)}	30 A					
V _R	600 V					
V _F at I _F	1.15 V					
t _{rr} (typ.)	30 ns					
T _J max.	175 °C					
Circuit configuration	Single					

FEATURES

- Low forward voltage drop
- Ultrafast recovery time
- 175 °C operating junction temperature
- · Low leakage current



- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION

Ultralow V_F , soft-switching ultrafast rectifiers optimized for discontinuous (critical) mode (DCM) power factor correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

MECHANICAL DATA

Case: D²PAK (TO-263AB), TO-262AA

Molding compound meets UL 94 V-0 flammability rating **Terminals:** matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Repetitive peak reverse voltage	V _{RRM}		600	V
Average rectified forward current	I _{F(AV)}	T _C = 122 °C	30	А
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	200	A
Operating junction and storage temperatures	T _J , T _{Stq}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	PARAMETER SYMBOL TEST CONDITIONS							
Breakdown voltage, blocking voltage	V_{BR}, V_{R}	$I_{R} = 100 \mu A$	600	ı	-			
Forward voltage	V _F	I _F = 30 A	-	1.4	2.0	V		
		I _F = 30 A, T _J = 150 °C	ı	1.15	1.35			
Reverse leakage current	I _R	$V_R = V_R$ rated	-	0.02	30			
Reverse leakage current		T _J = 150 °C, V _R = V _R rated	-	30	250	μA		
Junction capacitance	C _T	$V_{R} = 600 \text{ V}$	ı	20	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	ı	8.0	-	nH		

VS-ETU3006SHM3, VS-ETU3006-1HM3

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1 A, dI_F/dt = 50$	0 A/μs, V _R = 30 V	-	30	45		
Reverse recovery time	t _{rr}	T _J = 25 °C	I _F = 30 A dI _F /dt = 200 A/μs V _R = 200 V	-	45	-	ns A nC	
		T _J = 125 °C		-	100	-		
Dook room ourrent	I _{RRM}	T _J = 25 °C		-	5.6	-		
Peak recovery current		T _J = 125 °C		-	10	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	127	-		
		T _J = 125 °C		-	580	-		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C		
Thermal resistance, junction-to-case	R _{thJC}		-	0.95	1.2	°C/W		
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70			
Thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-			
Weight			-	2.0	-	g		
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)		
Mandana davias		Case style D ² PAK (TO-263AB) ETU3006SH			006SH			
Marking device		Case style TO-262AA	ETU3006-1H					

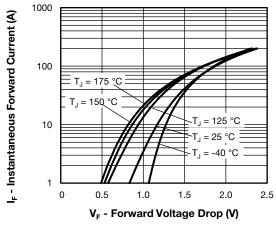


Fig. 1 - Typical Forward Voltage Drop Characteristics

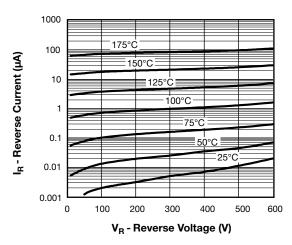


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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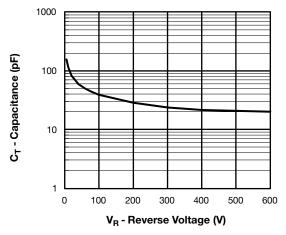


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

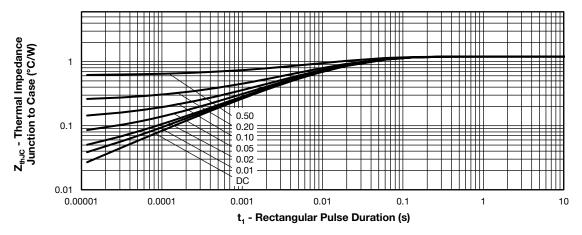


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

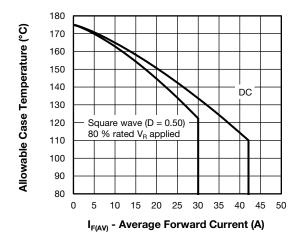


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

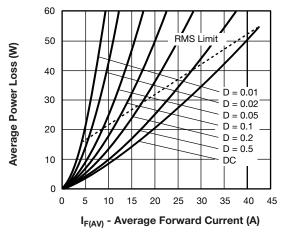


Fig. 6 - Forward Power Loss Characteristics

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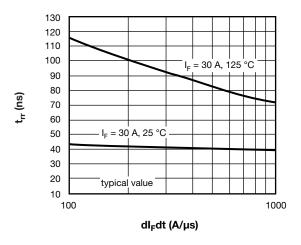


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

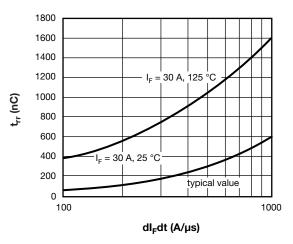


Fig. 8 - Typical Stored Charge vs. dl_F/dt

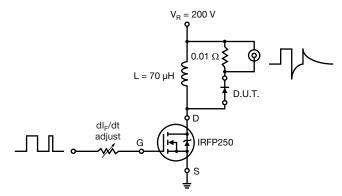
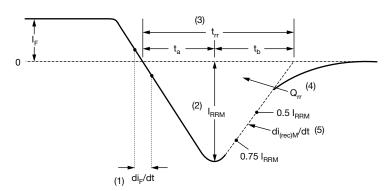


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

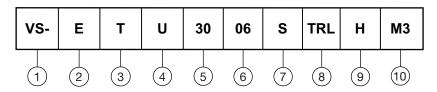
Fig. 10 - Reverse Recovery Waveform and Definitions

VS-ETU3006SHM3, VS-ETU3006-1HM3

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

- Circuit configuration

E = single

3 - T = TO-220

4 - U = ultrafast recovery time

5 - Current code (30 = 30 A)

6 - Voltage code (06 = 600 V)

7 - • S = D²PAK (TO-263AB)

- • -1 = TO-262AA

8 - • None = tube

- TRL = tape and reel (left oriented, for D²PAK (TO-263AB) package)

- TRR = tape and reel (right oriented, for D2PAK (TO-263AB) package)

9 - H = AEC-Q101 qualified

10 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-ETU3006SHM3	50	Antistatic plastic tube					
VS-ETU3006-1HM3	50	Antistatic plastic tube					
VS-ETU3006STRRHM3	800	13" diameter reel					
VS-ETU3006STRLHM3	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS						
Dimensions	D ² PAK (TO-263AB)	www.vishay.com/doc?95046				
Differisions	TO-262AA	www.vishay.com/doc?95419				
Dest seculine information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444				
Part marking information	TO-262AA	www.vishay.com/doc?95443				
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?95032				
SPICE model		www.vishay.com/doc?96775				



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		HES NOTES		NOTES SYMBOL MILLIMETERS INCHES		MILLIMETERS		HES	NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB

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TO-262

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	METERS	INC	INCHES			
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES		
Α	4.06	4.83	0.160	0.190			
A1	2.03	3.02	0.080	0.119			
b	0.51	0.99	0.020	0.039			
b1	0.51	0.89	0.020	0.035	4		
b2	1.14	1.78	0.045	0.070			
b3	1.14	1.73	0.045	0.068	4		
С	0.38	0.74	0.015	0.029			
c1	0.38	0.58	0.015	0.023	4		
c2	1.14	1.65	0.045	0.065			
D	8.51	9.65	0.335	0.380	2		
D1	6.86	8.00	0.270	0.315	3		
E	9.65	10.67	0.380	0.420	2, 3		
E1	7.90	8.80	0.311	0.346	3		
е	2.54 BSC		0.100	BSC			
L	13.46	14.10	0.530	0.555			
L1	-	1.65	-	0.065	3		
L2	3.36	3.71	0.132	0.146			

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- 5) Controlling dimension: inches
- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

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